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# Elevated temperature transmission Kikuchi diffraction in the SEM

## **Keywords**

TKD, in-situ annealing, solid state dewetting, Au thin-film

## **Abstract**

Transmission Kikuchi diffraction (TKD) facilitates automated orientation mapping of thin films in scanning electron microscopes (SEM). In this study TKD is applied for the first time to perform in-situ annealing experiments on gold thin films deposited on a MEMS-based heating system. The very local heating associated with this system enables reliable TKD measurements at elevated temperatures without notable disturbance from infrared radiation. The dewetting of an Au thin film into Au nanoparticles upon heating is followed with orientation mapping in a temperature range between 20°C and 900°C. The local thickness variation associated with the dewetting is observed qualitatively by observing the intensity of the transmitted beam, which decreases as the film thickness increases locally. The results of this study reveal that TKD is a well suited technique to study thin-film stability and solid state dewetting. Moreover, the outcome of this methodological study provides a baseline for further in-situ crystallographic studies of electron transparent samples in the SEM.

## **1. Introduction**

Since transmission Kikuchi diffraction (TKD) was introduced by Keller and Geiss [1,2] in 2012, the technique has received increasing interest and has been applied to investigate several material systems [3–11] within a large range of fields [1,4–8,10,12–14]. Additionally, a considerable focus has been directed to further understanding and optimising the technique [9,11,14–20]; besides improvements related to the acquisition software, and some new hardware developments [21–23].

Several authors have discussed TKD in comparison to EBSD and orientation mapping in TEM [12,24,25], pointing out its advantages and disadvantages. It is reasonable to see TKD as a complementary technique to both EBSD and TEM; however it is evident that the focus, up to now, has been concentrated on complementing EBSD with the additional spatial resolution of TKD [11,12,26–28]. It has been indicated previously that one disadvantage of TKD in comparison to EBSD lies in the requirement of having electron transparent samples, which leads to more demanding sample preparation [24]. Furthermore, the analysis of thinned samples or thin focused ion beam (FIB) lamellas prepared from bulk specimens limits the investigation area, which may not truly represent the bulk sample.

On the other hand, TKD provides opportunities to investigate electron transparent crystalline samples quantitatively in the SEM. Many samples, which were conventionally investigated only with the TEM, due to their resolution requirements or their small volume or thickness, can now also be investigated by TKD in the SEM. Considering that SEMs are more commonly accessible and relatively simpler to operate than TEMs, this perspective will most probably attract further attention and interest to the technique.

Solid state dewetting is a known phenomenon in which a continuous thin film will agglomerate at temperatures well below the film's melting temperature and form particles. The driving force for dewetting is the minimization of the total energy of surfaces and interfaces [29,30]. The dewetting

1 process of gold is known to be divided in three main stages: (i) hole nucleation and grain growth; (ii)  
2 hole growth and “finger” formation and (iii) film break up into separate particles [31,32]. Solid state  
3 dewetting depends on several parameters such as initial film thickness, deposition method,  
4 substrate, annealing temperature, time and atmosphere [29,31,33]. Furthermore, it is known that  
5 grain growth, texture, grain boundaries and triple junctions play an important role on the dewetting  
6 process [29,34,35].

7 While dewetting is associated with the disintegration of the film at elevated temperatures, which is  
8 detrimental for the performance of micro and nanodevices [36], it can also be employed as an  
9 effective tool for producing ordered nanoparticle arrays useful for various applications [30,37–40].  
10 Both fields have received considerable research interest and the dewetting process has been  
11 comprehensively reviewed [29,30,40,41] and widely investigated in the past decade. Within those  
12 investigations, electron microscopy was frequently applied to investigate the post-annealing film  
13 surface [42,43], whilst some in-situ microscopy investigation have recently been carried out [34,44–  
14 46]. However, only a few of these studies investigated the effect of crystallographic orientation on  
15 the dewetting process [31,35,46].

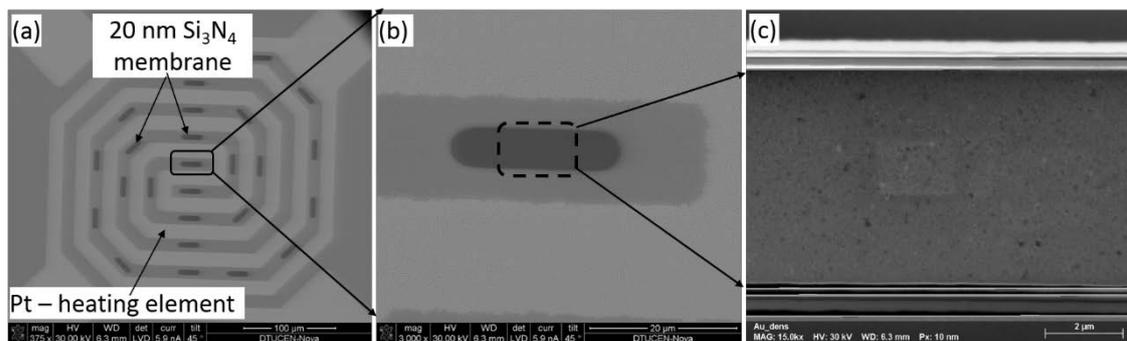
16 From the microstructural point of view, TKD is ideal to investigate solid state dewetting of thin films,  
17 as it combines an improved spatial resolution in comparison to EBSD, with the ability of investigating  
18 thin samples in an SEM. In the present work, this possibility is tested by means of performing in-situ  
19 annealing and dewetting of Au thin films deposited on a MEMS-based (Micro-Electro-Mechanical-  
20 Systems) heating holder with TKD in an SEM, with a particular focus on the demonstration of the  
21 capabilities of TKD for such in-situ heating experiments. The perspective of the technique will be  
22 demonstrated with respect to the potential impact on the in-situ characterization of dynamic  
23 phenomena in low-dimensional or nanosized materials.

24

## 25 2. Experimental details

26 To perform the in-situ TKD annealing experiments thin gold films (15 nm) were deposited by electron  
27 beam evaporation using a Wordentec QCL 800 (Wordentec Limited Shebbear, UK) on MEMS-based  
28 heating chips (Wildfire, DENSsolutions, Delft, The Netherlands). The film was deposited with a  
29 deposition rate of  $1\text{ \AA}/\text{s}$ , chamber pressure of  $3 \times 10^{-6}$  mbar and substrate temperature between  $17^\circ\text{C}$   
30 and  $20^\circ\text{C}$ . A quartz crystal microbalance (QCM) was used to determine the film thickness. Figure  
31 1(a) shows an SEM image of the heating chip, featuring several electron transparent windows of  $5\text{ }\mu\text{m} \times 20\text{ }\mu\text{m}$ ,  
32 with 20 nm thick amorphous silicon nitride membranes as support. Figure 1(b) shows  
33 the investigated window in the centre of the chip and Fig. 1(c) a STEM bright field image of the  
34 investigated window covered with the Au film. This image was obtained with the ARGUS<sup>TM</sup> solid  
35 state detector positioned below the sample.

36

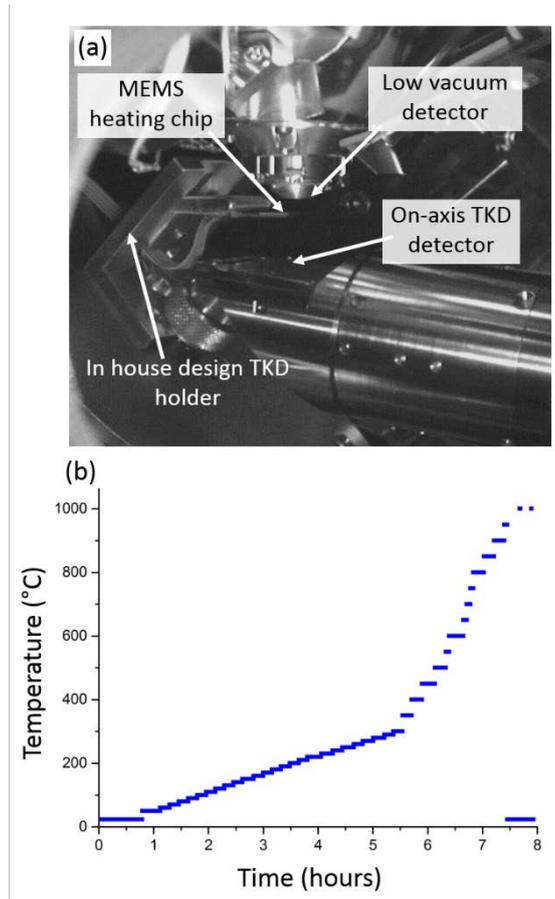


1 *Figure 1: Microscope experimental set-up configuration for in-situ TKD heating in an SEM: (a)*  
2 *Secondary electron image of the MEMS heating chip with 15 nm Au film. (b) Zoom on the*  
3 *investigated window on the centre of the chip (c) STEM bright field image of the Au film on the centre*  
4 *window. (DOUBLE COLUMN)*

5 The MEMS heating chips were mounted in an in house designed TKD holder. The temperature  
6 control of the MEMS chip was performed via the DENSsolution heating unit. The MEMS heating  
7 chips were mounted with the Au film facing the TKD camera (Au film positioned at the beam exit  
8 surface), since scattering events on the amorphous Si<sub>3</sub>N<sub>4</sub> membrane contribute to loss of the  
9 diffraction pattern as shown in [18]. Figure 2(a) shows the experimental set-up in the microscope  
10 chamber. The TKD experiment was performed in a FEI Nova Nanolab 600 SEM with a Bruker e-  
11 Flash OPTIMUS™ TKD detector, which allows on-axis TKD investigation of the sample. The chip  
12 was connected to the 45° pre-tilted heating holder and the stage was tilted accordingly to allow the  
13 sample to be at 0° tilt and give enough space for the OPTIMUS detector to be positioned underneath  
14 the sample. A low vacuum detector was connected to the microscope pole piece, and a water vapour  
15 pressure of 50 Pa was chosen for the experiments. The low vacuum mode was chosen to minimise  
16 drift and contamination of the sample, as demonstrated in [13,47] drift minimization can be achieved  
17 by reduction of electron charging effect. The electrons leaving the sample surface collide with water  
18 vapour molecules ionizing them and balancing out the sample charge [47]. The increase in chamber  
19 pressure however, can causes deterioration of the Kikuchi patterns. Utilizing a dedicated low vacuum  
20 detector that has a small beam gas path length, the adverse influence of chamber pressure on the  
21 Kikuchi pattern was minimized. Previous experiments on this sample have shown that the decrease  
22 in pattern quality is not significant at pressures below 60Pa.

23 Prior to the TKD investigation, the sample was plasma cleaned inside the microscope chamber using  
24 an Evactron decontaminator (XEI-Scientific, Redwood City, CA). The plasma cleaning was  
25 performed for 2 minutes at a pressure of 0.4 Torr and a Forward RF power of 12 Watts. The in-situ  
26 TKD experiment was performed at 30 kV beam energy with a beam current of 4 nA, an aperture of  
27 50 µm, a detector distance of 15 mm and a working distance of 5.7 mm. An area of approximately  
28 2.5 x 2.5 µm was investigated with a step size of 10 nm over a temperature range from 20°C to  
29 500°C and with step size of 20 nm from 550°C to 1000°C. A pattern resolution of 320 x 240 pixels  
30 was used, which resulted in an exposure time of 9 ms and a dynamical background correction was  
31 employed. In total, each mapped area was scanned for approximately 8 min (for the step size of 10  
32 nm) and 2 min (for the step size of 20 nm). Furthermore, at some selected temperatures, the entire  
33 membrane was investigated (an area of 15 µm x 5 µm) with a step size of 50 nm, to obtain an  
34 overview of the process over a larger area.

35 The sample was heated by an integrated heater coil (DENSsolution heating unit), allowing localised  
36 resistive heating directly on the sample support. The temperature readout was based on a resistivity  
37 measurement of the heater coil. Figure 2(b) shows the temperature versus time profile of the entire  
38 experiment. The temperature was increased between 50°C and 300°C by an increment of 10°C and  
39 after 300°C by an increment of 50°C. The TKD measurements were always performed at the  
40 respective elevated temperatures with exception of 950°C and 1000°C. During TKD measurements  
41 at 950°C, it was observed that no Kikuchi patterns were obtained from the sample, therefore the  
42 sample was cooled down to 23°C and measured at this temperature. The same procedure was  
43 repeated for 1000°C, at which temperature the sample was only kept for 1 min, and measured at  
44 room temperature. All heating and cooling to the respective temperature was performed within  
45 milliseconds.



1

2 *Figure 2: (a) Microscope chamber image at the experimental conditions (b) temperature versus time*  
 3 *profile of the in-situ TKD experiment. (SINGLE COLUMN)*

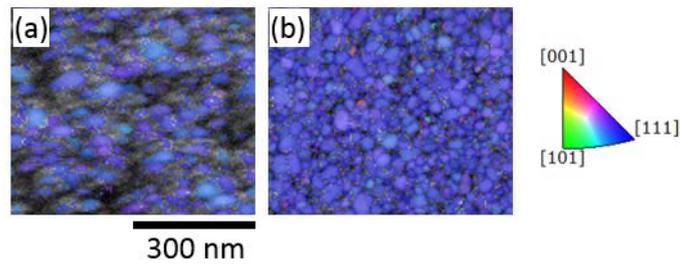
4 Data analysis was performed partly with ESPRIT (Bruker) and partly with OIM TSL (EDAX) software.  
 5 The ESPRIT was used for all pattern related data analysis, while OIM TSL was used for the analysis  
 6 of the film microstructure. Prior to data analysis, the data was processed to define a grain and to  
 7 eliminate dubiously indexed points. To this end, first a grain was defined as a region containing at  
 8 least 3 data points with the same orientation and with a misorientation larger than  $2^\circ$  to its neighbour.  
 9 All data points that did not satisfy these criteria were removed from the datasets. Additionally zero  
 10 solutions within a grain (points not touching a grain boundary) were cleaned (filled) to a maximum of  
 11 10 data points.

12

### 13 3. Results

14 As mentioned in the experimental details, the sample was plasma cleaned within the microscope  
 15 chamber prior to the investigation. In Figure 3, an example of the advantages of conducting such  
 16 cleaning is presented (sample: 20 nm of Au film deposited on a 20 nm Ti film). Figure 3(a) shows a  
 17 measurement conducted prior and figure 3(b) after 2 minutes plasma cleaning. Both maps were  
 18 measured with the same step size of 5 nm and the same pattern resolution, however the  
 19 improvement in pattern intensity after plasma cleaning was so significant that the map in (b) was  
 20 acquired more than 4 times faster than the map shown in (a), since the required exposure time could  
 21 be reduced significantly. The improvement is also evident on the drift minimization (results from the

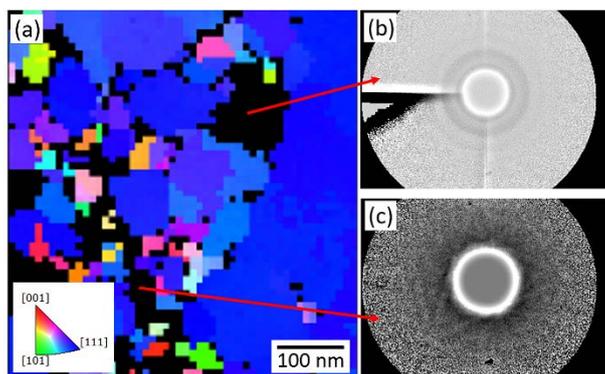
1 faster measurements) and on the number of indexed points, which increased from 45% in (a) to 80%  
2 in (b).



3  
4 *Figure 3: Example of TKD data improvement as result of plasma cleaning for a 20 nm Au thin film*  
5 *deposited on a 20 nm Ti film. (a) Inverse pole figure map before and (b) after plasma cleaning of the*  
6 *sample inside the microscope chamber. (SINGLE COLUMN)*

7 A preliminary investigation of the 15 nm Au film deposited by electron beam evaporation on  $\text{Si}_3\text{N}_4$   
8 windows reveals that the microstructure of the film is bimodal, comprising of smaller grains with a  
9 diameter in the range of 30 nm and larger grains with a diameter in the 150 nm range and no  
10 evidence of film discontinuity could be observed. Due to the presence of finer grains, it is  
11 advantageous to perform measurements with a step size of 3 to 5 nm, however such a small step  
12 size results in a relatively large measurement time (approximately 40 min to scan an area of  $2 \times 2$   
13  $\mu\text{m}$ ). Considering that the current study dealt with the investigation of dynamic processes (grain  
14 growth and film dewetting) a compromise was found by investigating the studied area with a relatively  
15 large step size of 10 nm, which allowed each map to be acquired in 8 minutes. Additionally, the size  
16 of the grains increased with the temperature and only in the lower temperature range, few grains  
17 were not indexed due to the chosen step size. Furthermore, at temperatures above  $550^\circ\text{C}$ , the step  
18 size was further increased to 20 nm, as the grains were considerably larger ( $d > 100$  nm) and the  
19 dewetting process significantly faster. In this way, the area was scanned in only 2 min.

20 Due to this step size choice, it was difficult to evaluate the starting point of dewetting by means of  
21 observing the number of indexed points, as the number continues to increase, due to grain growth,  
22 even after dewetting has started. Therefore, it was necessary to evaluate the patterns on the non-  
23 indexed areas of the raw data set (this means every point in the map, independent of any data  
24 processing applied in the map) to have reliable evidence of the start of the dewetting process. Figure  
25 4 shows two examples of a non-indexed pattern on the TKD map acquired at  $210^\circ\text{C}$ : Fig. 4(b) on a  
26 dewetted area of the sample and Fig. 4(c) on an area with very fine grains (in the range of 10-20  
27 nm). The difference between the two patterns is evident. In Fig. 4(c) Kikuchi lines are clearly visible,  
28 but indexing is difficult due to the fact that the grain size is close to the physical resolution of the TKD  
29 technique, and due to the overlapping of the patterns at the grain boundaries. In Fig. 4(b) no pattern  
30 is observed, indicating lack of crystalline material, i.e. only the  $\text{Si}_3\text{N}_4$  substrate is present.

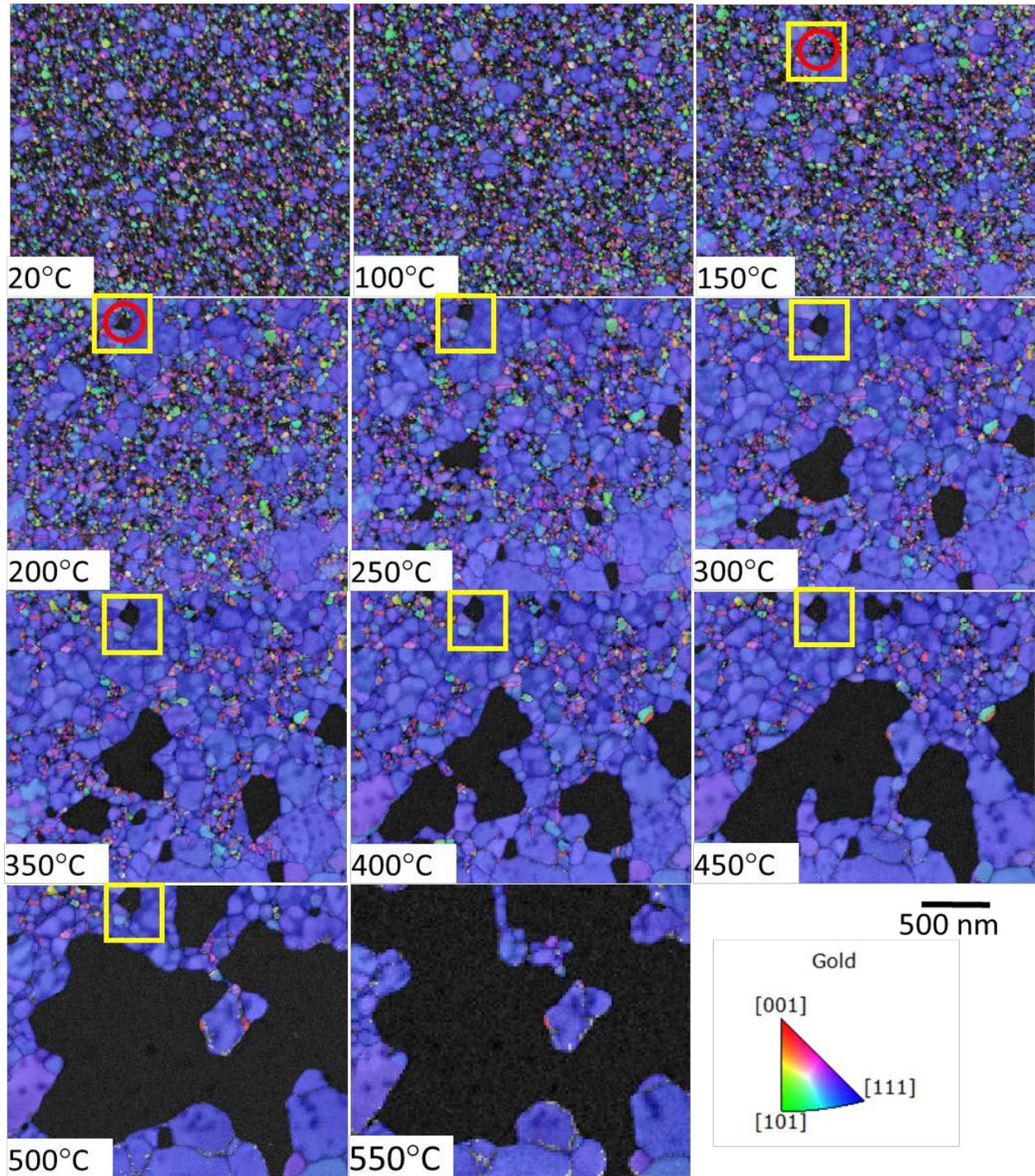


1

2 *Figure 4: (a) IPF map of the growth direction of the 15nm Au thin-film at 210°C, showing in black the*  
 3 *non-indexed areas consisting of dewetted regions and regions with very fine non-indexed grains. (b)*  
 4 *Recorded camera signal from a dewetted area of the sample revealing no pattern and (c) non-*  
 5 *indexed Kikuchi diffraction pattern from a fine grain region. (SINGLE COLUMN)*

6 Figure 5 shows some of the inverse pole figure (IPF) maps of the film growth direction (out of plane)  
 7 overlaid with pattern quality for temperatures varying from 20°C to 550°C (the full data with all  
 8 temperature increments is shown in supplementary material). All TKD measurements presented in  
 9 Figure 5 were performed at the respective temperatures and at the same window position. Sample  
 10 drift can be observed when comparing the microstructure between maps (see supplementary  
 11 material with all measurement increments) and it was more significant at lower temperatures (below  
 12 100°C). The IPF maps reveal that the film has a strong [111] out-of-plane texture, and that grains  
 13 with this preferential orientation tend to grow faster (abnormal grain growth), confirming results from  
 14 previous studies [34,35,48,49]. Grains oriented along this preferential orientation are, from this point  
 15 on, termed PO-grains and the ones deviating more than 15 degrees from it are termed non-  
 16 preferential oriented grains (non-PO). It is also observed that grain growth started at a temperature  
 17 below 150°C while holes are clearly visible at 200°C (highlighted with a red circle). By investigating  
 18 the patterns as described above (see Figure 4) at the position of the hole formed below 200°C  
 19 (highlighted with red circle in Figure 5), it was possible to determine that the hole had already formed  
 20 at 150°C (also highlighted with a red circle). Since saving all the pattern for all the maps requires  
 21 extremely large space, Kikuchi patterns were only saved for selected map (i.e. selected  
 22 temperatures), and it is therefore difficult to determine the exact temperature of formation of the first  
 23 hole. Furthermore, all holes were formed in the vicinity of non-PO grains, which are also the sites  
 24 that favour the growth of the holes. PO-grains, oriented along [111] can also delay hole growth, as  
 25 it can be observed in the yellow rectangle area, where a hole is formed at 150°C and grows until it  
 26 is completely surrounded by large PO-grains. The growth of this specific hole is then retarded until  
 27 500°C, while other holes in the film continue to grow.

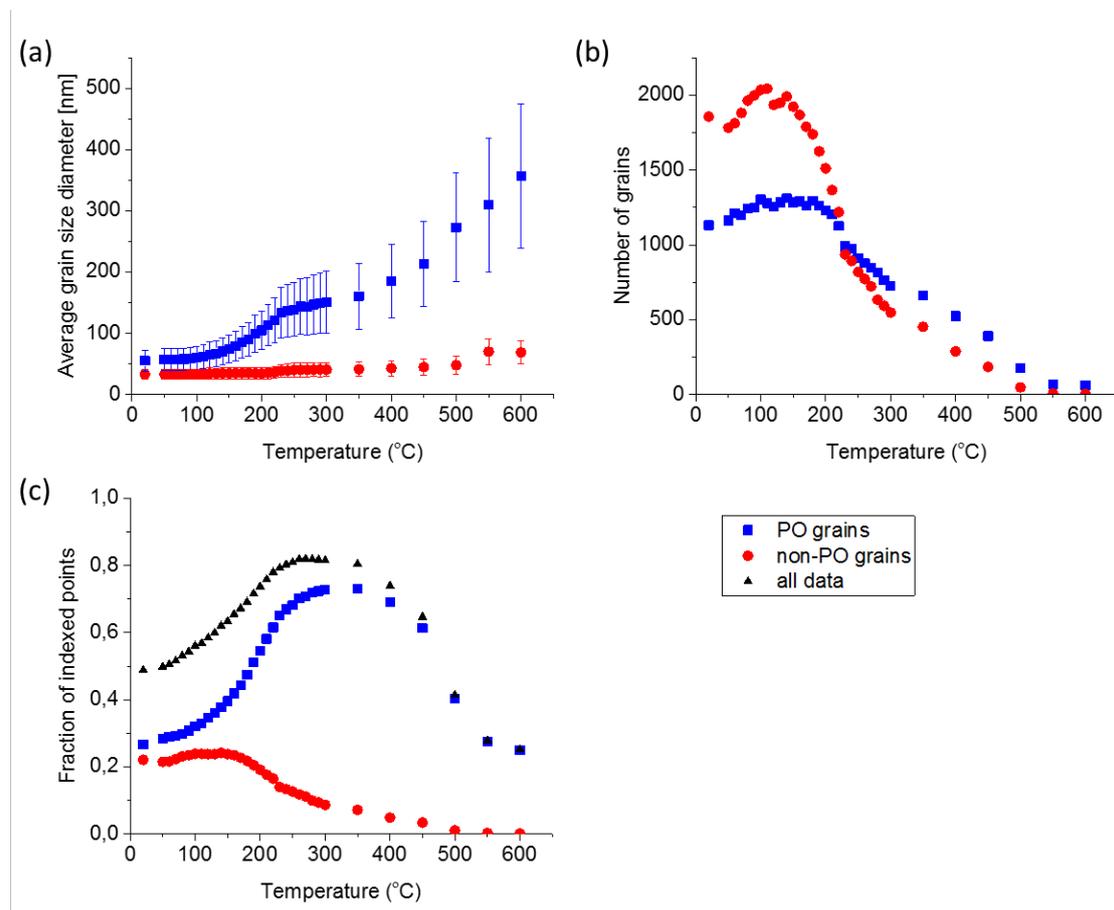
28



1  
 2 *Figure 5: Out of plane IPF maps at selected temperatures overlaid with pattern quality map showing*  
 3 *the grain growth, the formation of holes on non-PO grains and their subsequent growth. The red*  
 4 *circle highlights one of the first formed holes, while the yellow rectangle illustrates the delayed hole*  
 5 *growth of a hole surrounded by [111] PO oriented grains. (DOUBLE COLUMN)*

6 Since TKD measurements provide a large amount of data for each scanned point in the map (54000  
 7 points at the step size of 10 nm), quantitative data analyses can be obtained from this series of  
 8 measurements. As mentioned before, and clearly observed in Figure 5, two classes of grains are  
 9 distinct in the microstructure. Using this information, the orientation data was divided into two classes

1 of grains: i) PO-grains defined as grains with  $[111]$ //growth direction (using tolerance angle of  $15^\circ$ )  
 2 and ii) grains with other orientations (non-PO) and analysed separately. The average grain size  
 3 diameter evolution is shown in Figure 6(a) for annealing temperatures up to  $600^\circ\text{C}$  for both grain  
 4 classes separately. This graph confirms the images shown in Figure 5, revealing that grain growth  
 5 is evident for PO grains after  $120^\circ\text{C}$ . The PO grains are larger than non-PO ones from the starting  
 6 microstructure and grow considerably faster. By a temperature of  $220^\circ\text{C}$ , the PO average diameter  
 7 increases three-fold, while non-PO grains maintain their average size of  $33\text{ nm}$ ; up to  $550^\circ\text{C}$ ,  
 8 practically only PO grains grow. Figure 6(b) shows the number of grains of each class during  
 9 annealing, while Figure 6(c) shows the evolution of the fraction of indexed points for those two  
 10 classes of grains and for the entire data set. These data confirm again the observation of the images  
 11 in figure 5, showing that the fraction of indexed points and the number of non-PO grains start to  
 12 decrease at an annealing temperature of  $150^\circ\text{C}$ , which agrees with the starting point of hole  
 13 formation (the dewetting process). On the other hand, the fraction of PO indexed points increases  
 14 up to  $350^\circ\text{C}$ , while the number of PO grains starts to decrease already at  $180^\circ\text{C}$ , indicating that  
 15 these grains grow and coalesce before the dewetting of the film takes place.

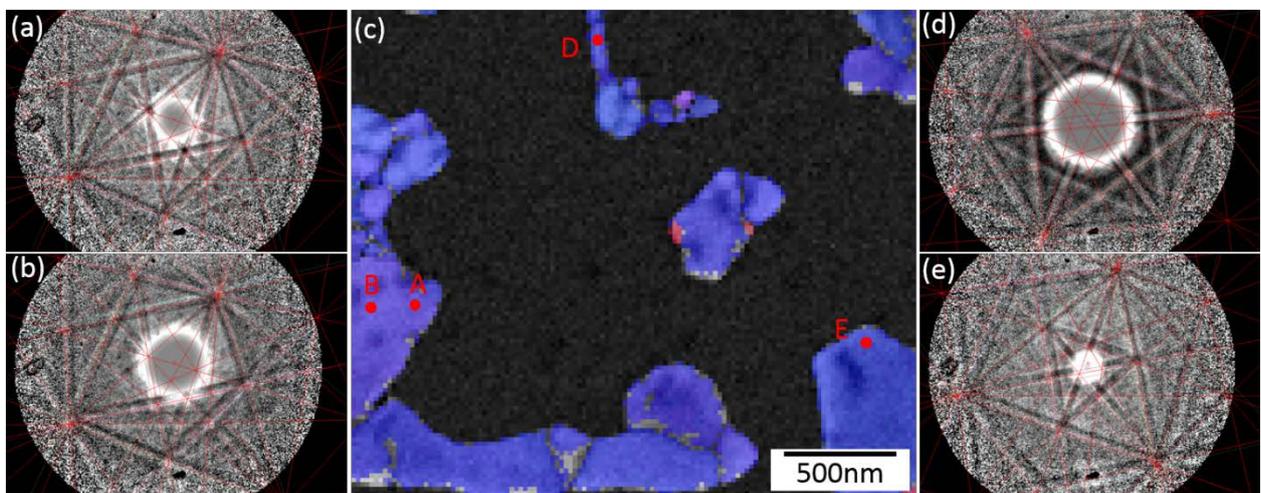


16

17 *Figure 6: Microstructure evolution for the two classes of grains. Blue squares: Preferentially*  
 18 *oriented grains (PO) are defined as grains with  $[111]$ //growth direction (using tolerance angle of*  
 19  *$15^\circ$ ); red circles: non- preferentially oriented grains (non-PO) defined as grains with other*  
 20 *orientations. Black triangles: all data, both grain classes together. (a) Evolution of the average*  
 21 *grain size diameter for the two classes of grains with temperature up to  $600^\circ\text{C}$ , (b) evolution of the*  
 22 *number of grains and (c) evolution of the fraction of indexed points with temperature. (DOUBLE*  
 23 *COLUMN)*

1 In solid state dewetting, once holes are formed they grow by edge retraction, resulting in mass  
2 accumulation and a local change in film thickness at the edge of the hole [29,31,33]. This local  
3 thickness variation can be clearly observed in the on-axis TKD patterns as the intensity of the  
4 transmitted primary beam is reduced with increasing thickness (Figure 7 a-e). The decreased  
5 intensity is observed as a decrease in the saturated area of the camera. Furthermore, the pattern  
6 contrast inverts when the film becomes significantly thicker (Figure 7 a, b and e) [9,17,50]. Both  
7 types of information can be qualitatively extracted from the TKD pattern and used to locate the areas  
8 where rim and fingers are formed [29,31,33]. Based on the intensity of the transmitted primary beam,  
9 it is easy to detect that the film is thinnest in the highlighted area **D** (finger) and thickest in **E** (rim).  
10 Indexing of patterns with inverted contrast is not optimal. Kikuchi lines are detected instead of bands,  
11 thus compromising the angular precision of the indexing routine. However, this error is not significant  
12 for the current investigation.

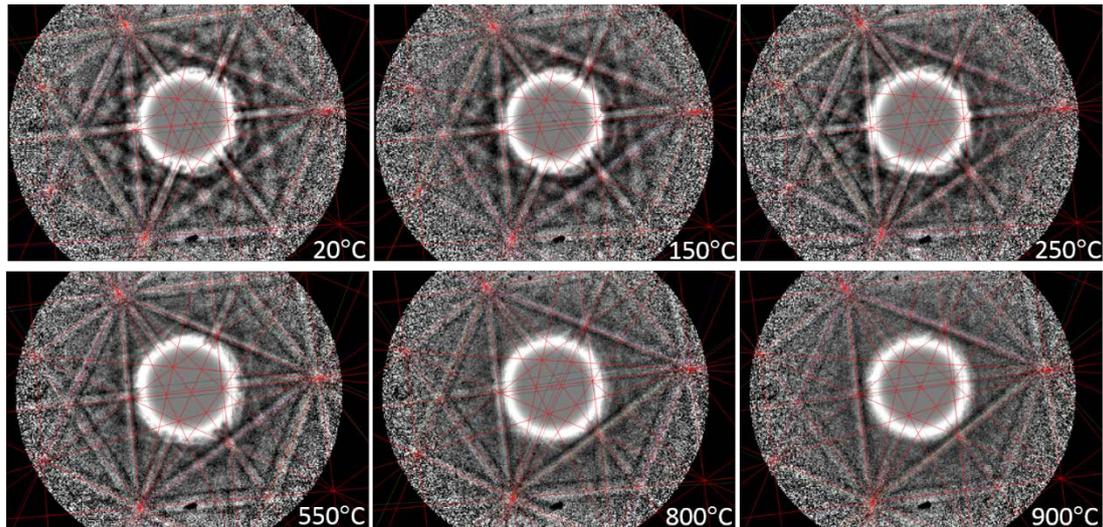
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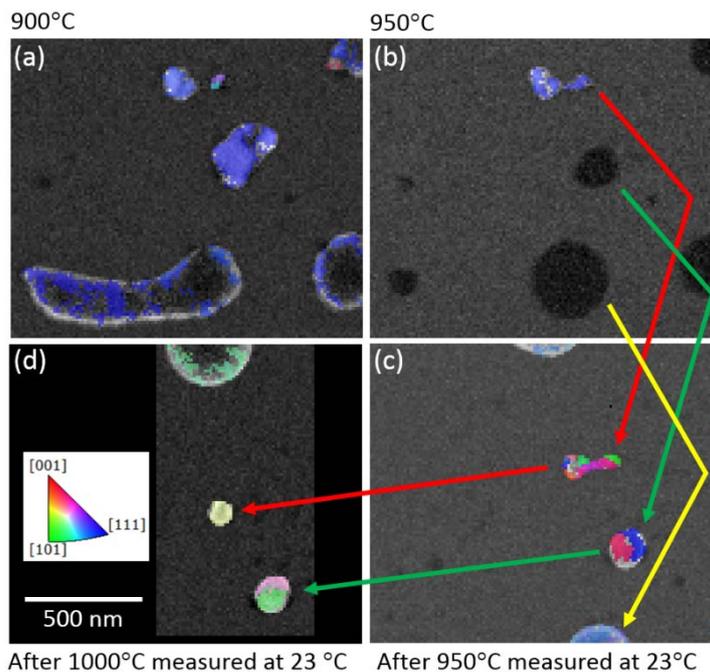
15 *Figure 7: TKD patterns at different locations of the sample, showing the thickness variation of the*  
16 *film during dewetting. c) IPF map overlaid with pattern quality map of the Au thin film at 600°C, the*  
17 *letters in the map indicate the location of the TKD patterns shown in a), b), d) and e). (DOUBLE*  
18 *COLUMN)*

19 Due to the very local heat achieved by MEMS-based heating devices, infrared radiation does not  
20 appear to significantly influence the CCD detector. Figure 8 shows on-axis TKD patterns obtained at  
21 different temperatures from approximately the same position. A clear signal to noise ratio reduction  
22 is observed with increasing temperature; however it is also noticeable that a reasonable pattern  
23 quality can be obtained even at high temperature and the indexing of these patterns posed no  
24 significant challenge for the software.



1

2 *Figure 8: TKD patterns obtained from approximately the same position at different temperatures.*  
 3 *(DOUBLE COLUMN)*

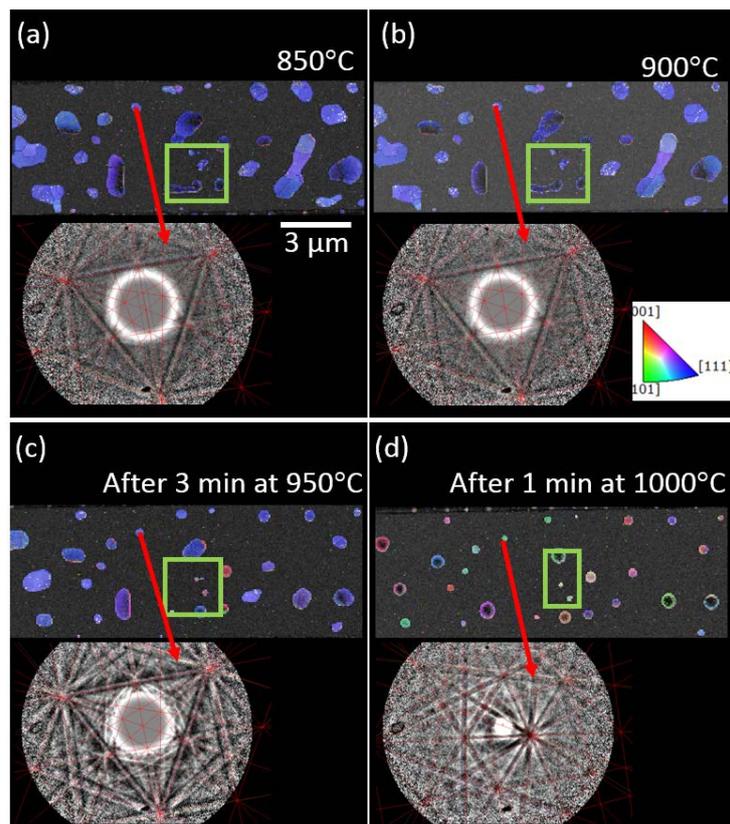


4

5 *Figure 9: IPF maps overlaid with pattern quality map of the film at high temperatures. a) Map*  
 6 *performed at 900°C, b) at 950°C, c) after cooling from 950°C and measuring at room temperature,*  
 7 *d) after cooling from 1000°C and measuring at room temperature. (DOUBLE COLUMN)*

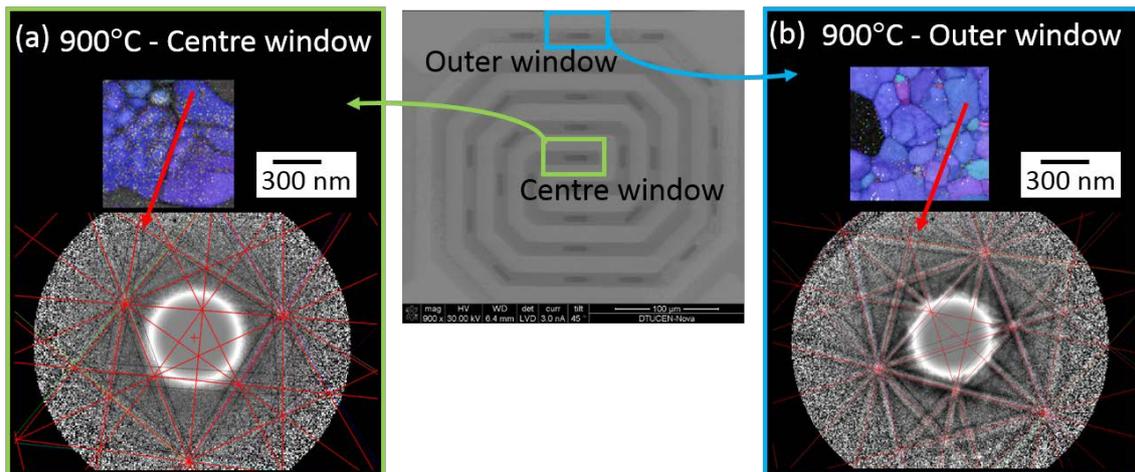
8 Obtaining TKD measurements at temperatures of 950°C and 1000°C was very challenging, because  
 9 the longer the sample remained at these temperatures, less crystalline material there was available  
 10 to measure, as the particles apparently started to melt. The sample was therefore kept at these  
 11 temperatures for only 3 minutes (950°C) (time to measure Figure 9(b)) and 1 min (1000°C) and  
 12 cooled down rapidly (in milliseconds) to room temperature (23°C). The map acquired at 950°C  
 13 (Figure 9(b)) shows clearly that most of the particles are not indexed at this temperature. Additionally,

1 comparing the map acquired at 950°C (Fig. 9(b)) to the subsequent map acquired right after cooling  
 2 down to 23°C (Figure 9(c)), it is evident that the particles have become crystalline again, however  
 3 with a new orientation. The same behaviour was observed after cooling from 1000°C (Figure 9(d)).  
 4 Figure 10 shows the out-of-plane IPF maps of the entire membrane (15 x 5 µm) measured at (a)  
 5 850°C, (b) 900°C, (c) after cooling down from 950°C and (d) after cooling down from 1000°C. The  
 6 previous investigated area (shown in Figure 5, 9 and in the supplementary material) is highlighted  
 7 with a green rectangle in the maps. Dewetting seems to be more advanced in the area where the  
 8 investigation was conducted in comparison with the other areas of the membrane (the size of  
 9 particles is significantly larger outside the green area, especially from 850°C to 950°C (a-c)). This  
 10 beam influence, however does not appear to be very significant for the final size of the particles, as  
 11 can be seen in the final result (Figure 10(d)). Related to this, it must also be pointed out that Au has  
 12 a melting point at 1064°C: in this experiment, the particles are changing their orientation after cooling  
 13 down from the high temperature treatment indicating that they might have melted. This lower melting  
 14 point could be related to the beam influence but also to the low vacuum condition with a water  
 15 pressure of 50 Pa. Additionally, the [111] preferential orientation of the Au particles/film is completely  
 16 lost after 1 minute at 1000°C, and no preferential orientation is formed after cooling. The repeated  
 17 heating to 1000°C and cooling of the sample leads to the reorientation of the Au particles each time  
 18 (data not shown here).



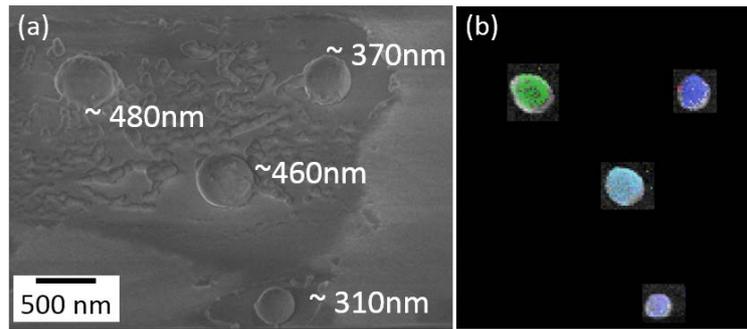
19  
 20 *Figure 10: Overview IPF maps from the entire window at different temperatures and TKD patterns*  
 21 *of the same particle obtained at the respective measurements a) at 850°C, b) 900°C, c) after*  
 22 *annealing at 950°C for 3 minutes and measuring at room temperature and d) after annealing at*  
 23 *1000°C for 1 minute and measuring at room temperature. The green rectangle in all the maps*  
 24 *highlights the area investigated in Figures 5, 9 and in the supplementary material. (DOUBLE*  
 25 *COLUMN)*

1 As shown in Figure 9 and mentioned above, some particles annealed for 3 min at 950°C did not  
 2 produce diffraction patterns at high temperature, and displayed new orientations after cooling,  
 3 indicating that they had melted and crystallized. This information raises a question about the lower  
 4 pattern quality observed at high temperature. Is the decrease in pattern quality related to infrared  
 5 radiation, or is the crystal disorder caused by the proximity of the melting point playing a role here  
 6 as well? To answer this question, a comparison was made between the pattern at high temperature  
 7 on the central window and on a window far away from the centre of the MEMS heating holder. It is  
 8 well known that there is a temperature gradient from the centre membrane to the outer membrane;  
 9 this gradient was shown by *Niekiel et al.* [51] to be in the order of 150°C. Considering this  
 10 temperature gradient, when the holder is set to 900°C at the central window, a window at the edge  
 11 should be at approximately 750°C: the infrared radiation is independent of which window the  
 12 measurement is performed on. However, dewetting at the outer window is not so advanced due to  
 13 the lower temperature and the melting of the Au has not yet close. Figure 11(a) shows an IPF map  
 14 and a pattern obtained from the central membrane at 900°C and Fig. 11(b) shows the map and the  
 15 pattern obtained from the outer membrane with the heating set to the nominal value of 900°C (but  
 16 with the film at the estimated value of 750°C). This result suggests i) that infrared radiation is not  
 17 drastically influencing the camera, as the patterns are sharp and with a high signal to noise ratio on  
 18 the outer membrane, but are not on the central membrane and ii) that the loss of sample crystallinity  
 19 is the main factor causing the degradation of the pattern quality at such high temperatures.



20  
 21 *Figure 11: TKD map and Kikuchi pattern at 900°C in two locations of the MEMS heating holder: (a)*  
 22 *on the central window and (b) on the outer window. The temperature gradient between the windows*  
 23 *was estimated to be in the order of 150°C [51]. (DOUBLE COLUMN)*

24 After the experiment was finished, the sample was placed upside down for SEM imaging (with the  
 25 Au particles facing the beam entrance surface). Figure 12(a) shows a secondary electron image  
 26 obtained with the through lens detector of the particles at the investigated area with an estimated  
 27 size of the particles highlighted in the image; Fig. 12(b) shows a TKD measurement of the same  
 28 particles, revealing how TKD orientation maps can be obtained from Au particles of almost 500 nm  
 29 in thickness.



1

2 *Figure 12: (a) Secondary electron image of the Au nanoparticles after the experiment with highlighted*  
 3 *estimation of the particles size. (b) TKD orientation map of the same nanoparticles in (a). (SINGLE*  
 4 *COLUMN)*

5

#### 6 **4. Discussion**

7 It is important to point out that, although knowledge about thin-film Au dewetting was obtained in this  
 8 work, this study primarily used Au dewetting as an example for investigating the possibilities of in-  
 9 situ TKD. Therefore, although some microstructure characteristics associated with the dewetting of  
 10 Au have been presented and briefly discussed in this paper, a detailed investigation of the process  
 11 is beyond the scope of this work and will be discussed in future reports. In this section, the in-situ  
 12 TKD results will be discussed, areas of potential improvement will be addressed and the prospects  
 13 of the technique will be outlined.

14 Measurement speed is an extremely important parameter for investigating dynamic events. Often  
 15 the increase of the measurement speed is associated with compromises. In this work, a compromise  
 16 was made in terms of spatial resolution (using a step size of 10 nm instead of more appropriate 3  
 17 nm) to maintain reasonable measurement area and time. The measurement time of 8 minutes was  
 18 acceptable at the lower temperature range, but not necessary at higher temperatures (above 500°C),  
 19 where the process was faster. Conversely, since both dewetting and grain growth commenced  
 20 before this temperature of 500 °C was reached, and all microstructural features became larger than  
 21 the starting microstructure, it was possible to increase the measurement speed by further increasing  
 22 the step size at high temperatures.

23 Further improvements in the measurement speed can be achieved by increasing beam current, by  
 24 decreasing pattern resolution, or conducting the experiments in high vacuum. Increasing beam  
 25 current is associated with a decrease in spatial resolution and an increase in sample contamination.  
 26 Decreasing pattern resolution can be a good solution, especially when the patterns are of very good  
 27 quality, as it has been shown in this example. However, indexing can be compromised on areas with  
 28 low pattern quality, particularly at high temperature and on thicker samples, where contrast inversion  
 29 of the patterns is observed. The vacuum condition is also related to pattern quality, since the water  
 30 vapour of the low vacuum mode can degrade the diffraction pattern quality [47].

31 Prior to any in-situ experiments, all these parameters must be investigated for every individual  
 32 sample within the objectives of the work, so that the optimized conditions can be found. In this study,  
 33 a further increase in beam current ( $I > 4$  nA) had the same effect as increasing the step size, however  
 34 with the disadvantage of increased contamination. Since an increase of the step size was more  
 35 significant in the initial steps of the experiment, while increased contamination would compromise  
 36 the pattern quality at higher temperatures, the increase in step size was chosen as the best  
 37 compromise. Decreasing the pattern resolution was also not favourable for the high temperature

1 patterns, particularly due to the local thickness variation of the film at high temperature and the  
2 further degradation of the pattern associated with that. The low vacuum condition chosen in this  
3 experiment, originates from experience with other samples deposited on silicon nitride membranes  
4 and measured with TKD. It was observed that both drift and charging were minimised in low vacuum  
5 conditions with minimal pattern degradation. Additionally, a low vacuum condition contributes to  
6 reduced sample contamination, due to reaction of water molecules with the carbon hydroxide forming  
7 on the sample surface. Further investigation and experience of high temperature measurements are  
8 required to properly evaluate the best vacuum for optimized pattern acquisition conditions.

9 Plasma cleaning of the sample prior to TKD experiments, on the other hand, revealed only  
10 advantages, as shown in the maps of Figure 3. The improvement in pattern quality and the  
11 consequently enhanced measurement efficiency is crucial for dynamic experiments, which require  
12 fast and multiple scans in the same position. The advantage of plasma cleaning is however not  
13 restricted to dynamic investigations and is recommended for all high resolution TKD experiments.  
14 Plasma cleaning the sample inside the microscope chamber is advantageous, as the chamber and  
15 the holder are cleaned simultaneously.

16 Although solid state dewetting is a well-studied process, there are still areas to be explored, as for  
17 example the starting point of hole formation. The observations shown in Figure 4 indicate that TKD  
18 has the potential to provide answer to that question, as there is a clear distinction between the  
19 detector signal obtained from very fine grains (here not always indexed by the software) and holes.  
20 Using this distinction in an automated way may allow one to track the exact position of hole formation,  
21 and fully characterize the microstructure at this location. However, in this study only a manual  
22 investigation was performed due to software restrictions. It is important to point out that the minimum  
23 size of a hole that can be detected by this methodology is limited by the physical spatial resolution  
24 of TKD in on-axis configuration, which has been shown in [52] to be in the order of 12 nm.

25 The detailed investigation of hole formation will be subject of another study, since for such a detailed  
26 investigation a finer map step size would be required, so that all the possible sites for hole formation,  
27 like grain boundaries and triple junctions, are well characterized from the initial microstructure.  
28 Furthermore, this method requires the Kikuchi patterns to be saved for every map at all temperature  
29 increments, which was not the case for this investigation. Such a study would also benefit from the  
30 combination of high resolution STEM images and TKD orientation maps for a more comprehensive  
31 characterization of the hole's nucleation sites. This combination was not applied in the current study,  
32 because each image technique requires a different detector insertion length, and consequently is  
33 combined with increased experimental time and drift. Such a combination is however possible,  
34 particularly when pseudo-in-situ experiments (heating and cooling within the microscope, but  
35 measuring always at room temperature) are conducted and when using the STEM and TKD  
36 combination as presented by Brodusch and co-workers [11,15] in the off-axis TKD configuration.

37 Figures 5 and 6 illustrate some of the information that can be obtained by in-situ dewetting of an Au  
38 film in combination with TKD. Evolution of grain size, texture, grain boundaries, and holes, can be  
39 tracked throughout the process with high resolution, accuracy and statistical significance. These  
40 figures, in combination with the full data presented in the supplementary materials, clearly reveal  
41 that grain growth occurs predominantly on grains with [111] out of plane orientations, and that it  
42 starts at relatively low temperatures ( $T < 150^{\circ}\text{C}$ ). This abnormal grain growth of preferential oriented  
43 grains is well known and has been proposed to be a surface-energy-driven secondary grain growth  
44 mechanism [34,35,48,49]. Furthermore, the first observed hole was also formed below  $150^{\circ}\text{C}$ .  
45 However, to the authors knowledge, most of the published microscopy studies on dewetting  
46 concentrate on high temperature investigations ( $T > 400^{\circ}\text{C}$ ). Taking the current results in

1 consideration it might be important to set the focus on understanding in more detail the  
2 microstructure modification occurring in thin films at the lower temperature range, particularly with  
3 respect to the fabrication and performance of nanodevices.

4 The in-situ experiments presented in this work have shown that TKD measurements on Au thin-films  
5 can be performed at temperatures varying from 20°C to 900°C without considerable problems (see  
6 Figure 8 and supplementary material), but measurements at 950°C and 1000°C were impossible  
7 (see Figure 9). The temperature limit in the current study was however imposed by the material and  
8 its proximity to the melting temperature (as demonstrated in Figure 11) and not by the TKD camera  
9 or the heating holder. Due to the very local heating of such MEMS heating holders, infrared radiation  
10 is apparently minimised. The comparison of patterns obtained in the inner and outer membranes,  
11 while heating the sample to 900°C (Figure 11), has given a clear indication that the detector is not  
12 significantly influenced by infrared radiation. The decrease in signal to noise ratio, observed at high  
13 temperatures (Fig. 8 and 9) is most probably a result of crystal disorder, being a consequence of the  
14 proximity of the melting point of the sample. Repeating the same experiment with a high melting  
15 point material ( $T_m > 1300^\circ\text{C}$ , which is the holder limiting temperature) provides a better indication of  
16 the real limit of TKD at high temperature.

17 The lower melting point of the Au particles observed in this work can be related to the interaction of  
18 the electron beam with the sample, but also to lattice vibrations increasing locally the temperature  
19 and to the vacuum conditions. In figure 10c for example, it can be observed that after exposing the  
20 sample for 3 minutes at 950°C, only the area, which has been previously investigated (highlighted  
21 in green) shows particles with different crystal orientation, indicating that only this area could have  
22 already reached the melting point and crystallized again after cooling. This suggests that beam  
23 interaction plays a role in the process. On the other hand after heating up the sample to 1000°C and  
24 cooling down again all particles changed their orientation. Since the melting point of Au particles with  
25 diameter above 100 nm should be equal to the bulk material [53], this deviation of approximately  
26 60°C suggests that other factors play a role. Furthermore, throughout the experiment the  
27 temperature measured at the heating coil is assumed to be the same as the one in the sample,  
28 based on the results presented in [51], where very little deviation between the sample temperature,  
29 and the read-out temperature was observed. Further experiments to better understand this effect  
30 would be of great interest, but are beyond the scope of this work.

31 It has being widely discussed in TKD studies that the technique is significantly influenced by sample  
32 thickness [1,12,17,18,24,54]. In particular, on-axis TKD patterns reveal different features depending  
33 on the thickness of the sample [17]. In on-axis TKD the thickness variation can be identified by the  
34 intensity of the directly transmitted primary beam signal at the detector positioned below the sample.  
35 The thicker the sample, the less saturated the camera is and thereby a smaller area of the camera  
36 appears overexposed. In this work, this thickness dependence is very useful, as it gives an indication  
37 about the local thickness variation caused by the mass accumulation of the Au during dewetting (see  
38 Figure 7). Currently this additional information can only be treated qualitatively, as there may be  
39 other parameters influencing this intensity, as for example crystal orientation. Kikuchi pattern  
40 contrast inversion with increasing film thickness poses a significant challenge to the automated  
41 indexing routine of the TKD software, and deteriorates the angular precision of indexing.  
42 Improvements to the indexing routine to take this effect into account are of high importance. As long  
43 as such improvements are not established, evaluating local orientation changes during the dewetting  
44 process should be carried out with caution, as when rims are formed and the thickness increases,  
45 contrast inversion can indicate a false local orientation change (grain rotation).

1 Although the TKD patterns are significantly influenced by sample thickness, it is possible to obtain  
2 indexable patterns from Au films with a thickness from 15 nm to Au particles of almost 500 nm, as  
3 shown in Figure 12. However, from Figure 10(d) it is clear that there is a maximum thickness limit,  
4 as particles with a diameter larger than 500 nm could not be fully indexed. Especially at the centre  
5 of those particles, where the thickness is approximately equal to the particle diameter, no Kikuchi  
6 patterns were observed. This thickness range is material dependent and has already been  
7 demonstrated for some materials [12,17,18,24]. It is important to point out, that both spatial resolution  
8 and angular precision are considerably reduced on large sample thicknesses, due to beam  
9 broadening and dynamical diffraction effects causing contrast reversal, complicating the indexing of  
10 the patterns. The determination of the precise thickness range, over which high resolution orientation  
11 maps of Au can be obtained, requires a systematic pattern contrast investigation on a known  
12 thickness. This is not the case of this experiment, as the thickness is varying during the experiment,  
13 and although indication of this variation is present on the pattern, no absolute value can be extracted  
14 from it. Therefore, the results provided here indicate only the thickness range in which indexable  
15 patterns can be obtained, but not the range in which high resolution TKD orientation data can be  
16 acquired.

17 MEMS-based heating holders are widely used in TEM heating experiments due to low drift, low mass  
18 and fast response. These advantages are very useful for in-situ TKD. The results presented in this  
19 work also reveal that infrared radiation is minimised and TKD investigations can be performed at  
20 very high temperatures. In the literature it has been described how the chip membrane tends to bulge  
21 at high temperature [51]. *Niekief et al.* reported bulging of up to 11  $\mu\text{m}$  at 800°C [51]. Such bulging  
22 of the membrane would result in a change of detector geometry (working distance, detector distance,  
23 and consequently pattern centre calibration), which is directly related to the indexing routine of the  
24 system. However, as those geometrical parameters are defined in the millimeter range, a membrane  
25 bulging of approximately 11  $\mu\text{m}$  should have a negligible influence on pattern calibration.  
26 Furthermore, since the capture angle of the TKD patterns is large enough to allow indexing of several  
27 bands and multiple zone axis, this slight geometrical misalignment is presumably not critical for a  
28 total orientation determination. No clear indication of film bulging could be observed during the  
29 experiments. However, 11  $\mu\text{m}$  of membrane bulging would contribute to an orientation change of the  
30 grains causing errors in the indexing. Since bulging of the membrane is expected at relatively high  
31 temperatures, where the particles thickness also contributes to the decrease in orientation precision,  
32 further experiments would be required to confirm if bulging of the membrane is influencing the TKD  
33 orientation precision or not.

34 Beam induced thermal drift, on the other hand, was noticeable between maps and substantially  
35 stronger at temperatures below 200°C, in the order of 200-300 nm. Map distortion was also  
36 observed, and again more significant at lower temperature, therefore most probably associated with  
37 beam induced effect. Due to the lower energy of the electrons in the SEM, the beam interaction with  
38 the sample is significantly larger than in the TEM and consequently the beam induced thermal effect  
39 is more significant. Thermal drift is quite significant in TKD, and has been reported by various authors  
40 [6,21,24,55]. The significant decrease of sample drift after a couple of hours during the experiment  
41 indicates that the sample stabilizes under the beam and drift is minimised with time. The thermal  
42 effect of the beam could also be influencing the dewetting process, as it was observed in Figure  
43 10(a-c), where dewetting is more advanced in the investigated areas (highlighted in green) compared  
44 to other areas of the membrane. Furthermore it could be that the enhanced conductivity at higher  
45 temperatures is also playing a role in reducing drift effects. The detailed investigation of these effects  
46 is, however, beyond the scope of this publication.

1 Although this study was only performed with the on-axis TKD configuration, it is not restricted to this  
2 configuration. Measurement speed, however, could be a significant challenge for the off-axis  
3 configuration, as it has been reported that on-axis TKD can be up to 20 times faster than off-axis  
4 TKD [55]. Conducting a pseudo-in-situ experiment should not be a problem for any configuration.  
5 One advantage of off-axis TKD configuration, would be the possibility of obtaining dark field images  
6 of the sample simultaneously with the orientation map, without camera movements or the  
7 combination with a STEM detector located below the sample as proposed in [11,15].

8 It is also important to mention that the oversaturated area in the centre of the screen does not  
9 noticeably compromise the indexing of the pattern, as also shown in [52], as bands are detected  
10 even though they are partially oversaturated. The band contrast map on the other hand, is disturbed  
11 by the acquisition of the transmitted beam intensity, leading to conditions where it is impossible to  
12 distinguish between the dewetted area and the non-indexed finer grains by means of the pattern  
13 quality. Software improvements in this regard would be very advantageous.

14 MEMS heating holders are certainly ideal for investigation of nanoparticles, nanowires and thin films,  
15 however they are not limited to those samples. FIB lift out lamellas can also be positioned on the  
16 membranes as demonstrated in [56].

17

## 18 **5. Conclusions**

19 The combination of very local heating and TKD is well suited for studying thin-film dewetting  
20 processes and has a large prospective in materials research. The small volume and very local  
21 heating minimises infrared radiation, which does not significantly compromise TKD patterns at high  
22 temperature. Drift is only significant at the beginning of the experiments, and could be minimised by  
23 allowing the sample to stabilise under the beam before starting the experiments. Plasma cleaning  
24 the sample prior to the experiments is an effective way to increase measurement speed and improve  
25 pattern quality. TKD patterns can be obtained from Au in a thickness range between 15 and 500 nm,  
26 although contrast inversion compromises the precision of orientation determination on thick samples.  
27 Therefore, software improvements for dealing with the effect of thickness variation on the patterns  
28 are very much required. This work nicely demonstrates the capability of high temperature TKD  
29 characterization of nanocrystalline thin films. The combination of high resolution imaging and  
30 orientation mapping under the influence of temperature in an SEM opens opportunities for scientific  
31 studies that were not accessible previously. Further development of even more stable MEMS heaters  
32 and software will pave the way for making in-situ TKD of low-dimensional materials routinely  
33 accessible as a complementary characterization technique within materials science.

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## 38 **Data availability**

39 The raw/processed data required to reproduce these findings cannot be shared at this time due to  
40 technical or time limitations.

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34